

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S23	41	(insulat\$3 dielectric) with stress with tensil\$4 with ?Pa.bi.	US-PGPUB; USPAT	OR	ON	2005/03/10 14:17
S25	67	(bump with polymer with metal\$3 with pad) and (flip adj1 chip).bi.	US-PGPUB; USPAT	OR	ON	2005/03/14 14:10
S26	333	(bump with (conduct\$3 adj1 polymer)) and (flip adj1 chip).bi.	US-PGPUB; USPAT	OR	ON	2005/03/14 14:11
S27	319	S26 not S25	US-PGPUB; USPAT	OR	ON	2005/03/14 14:11
S28	153	S27 and (\$5resist (photo adj1 resist) \$5mask)	US-PGPUB; USPAT	OR	ON	2005/03/14 14:12
S29	162	S27 and (\$5resist sacrific\$5 (photo adj1 resist) \$5mask)	US-PGPUB; USPAT	OR	ON	2005/03/15 08:00
S32	91	((metal conduct\$3) adj3 bump adj pad) and (flip adj1 chip).bi.	US-PGPUB; USPAT	OR	ON	2005/03/15 06:56
S33	17	((conduct\$3 adj1 (polymer polyimide)) with (photoresist (photo adj1 (resist mask)))) and (flip adj1 chip).bi.	US-PGPUB; USPAT	OR	ON	2005/03/15 07:40
S35	10	(polymer with spin\$4 with (cur\$3 bak\$3)) and S33	US-PGPUB; USPAT	OR	ON	2005/03/15 08:01
S36	67	(bump with polymer with metal\$3 with pad) and (flip adj1 chip).bi.	US-PGPUB; USPAT	OR	ON	2005/03/15 08:00
S37	333	(bump with (conduct\$3 adj1 polymer)) and (flip adj1 chip).bi.	US-PGPUB; USPAT	OR	ON	2005/03/15 08:00
S38	319	S37 not S36	US-PGPUB; USPAT	OR	ON	2005/03/15 08:00
S39	162	S38 and (\$5resist sacrific\$5 (photo adj1 resist) \$5mask)	US-PGPUB; USPAT	OR	ON	2005/03/15 08:00
S40	1	(polymer with spin\$4 with (cur\$3 bak\$3)) and S39	US-PGPUB; USPAT	OR	ON	2005/03/15 08:07
S41	1	(polymer with spin\$4 with (cur\$3 bak\$3)) and S37	US-PGPUB; USPAT	OR	ON	2005/03/15 08:02
S42	20	(polymer with spin\$4) and S39	US-PGPUB; USPAT	OR	ON	2005/03/15 08:02
S43	1	((conduct\$3 adj1 polymer) with spin\$4 with (cur\$3 bak\$3)) and (flip adj1 chip).bi.	US-PGPUB; USPAT	OR	ON	2005/03/15 09:12
S44	17	((conduct\$3 adj1 polymer) with spin\$4 with (cur\$3 bak\$3)).bi.	US-PGPUB; USPAT	OR	ON	2005/03/15 08:15
S45	0	(photolithography with (positive adj1 resist) with (negative adj1 resist)) and packag\$3.bi.	US-PGPUB; USPAT	OR	ON	2005/03/15 08:16

S46	10	(photolithography with (positive adj1 resist) with (negative adj1 resist)).bi.	US-PGPUB; USPAT	OR	ON	2005/03/15 08:16
S47	1	((conduct\$3 adj1 polymer) with (polish\$3 etch\$3 remov\$3) with grain) and (flip adj1 chip).bi.	US-PGPUB; USPAT	OR	ON	2005/03/15 09:14
S50	1	((polymer) with (polish\$3 etch\$3 remov\$3) with grain) and (flip adj1 chip).bi.	US-PGPUB; USPAT	OR	ON	2005/03/15 09:14
S51	176	((polymer) with (polish\$3 etch\$3 remov\$3) with grain).bi.	US-PGPUB; USPAT	OR	ON	2005/03/15 09:19
S53	11	S51 and packag\$3	US-PGPUB; USPAT	OR	ON	2005/03/15 09:16
S54	479	(polymer with (polish\$3 etch\$3 remov\$3) adj1 pad).bi.	US-PGPUB; USPAT	OR	ON	2005/03/15 09:20
S55	383	S54 and CMP	US-PGPUB; USPAT	OR	ON	2005/03/15 09:24
S56	9	(polishing adj1 pad) with grain with polymer.bi.	US-PGPUB; USPAT	OR	ON	2005/03/15 09:27
S57	0	(CMP with (conductive adj1 polymer)) and (flip adj1 chip).bi.	US-PGPUB; USPAT	OR	ON	2005/03/15 09:29
S58	0	(CMP with (conductive adj1 polymer)) and (packag\$3).bi.	US-PGPUB; USPAT	OR	ON	2005/03/15 09:28
S59	0	(CMP with (conductive adj1 polymer)).bi.	US-PGPUB; USPAT	OR	ON	2005/03/15 09:29
S60	484	(CMP with (polymer)).bi.	US-PGPUB; USPAT	OR	ON	2005/03/15 09:29
S61	9	S60 and (flip adj1 chip).bi.	US-PGPUB; USPAT	OR	ON	2005/03/15 09:34
S62	0	((polishing adj1 pad) with (small\$3 adj1 grain)) with polymer.bi.	US-PGPUB; USPAT	OR	ON	2005/03/15 09:35
S67	3	((polishing adj1 pad) with (grain)) and (packag\$3).bi.	US-PGPUB; USPAT	OR	ON	2005/03/15 09:36